

Tack Flux No-Clean for Low Temp in Jar 150g

Product Highlights

Ideal for all rework, solder, de-solder and reflow applications
 Non-corrosive, non-conductive, no-clean
 Tack flux will not run all over PCB when applied
 Has a pleasant odor
 Excellent wetting
 Easily cleaned with isopropyl alcohol (IPA)
 Attachment of BGA spheres
 Soldering flip chip components
 Long stencil life
 Wide process window
 Clear residue
 Commonly used with Sn42/Bi58, Sn42/Bi57.6/Ag0.4, and Sn42/Bi57/Ag1 alloys, which melt at 138°C (281°F)
RoHS 3 and REACH compliant



Representative Photo Only
 Please note flux color may vary from light yellow to orange/brown

Specifications

Flux Type:	Synthetic No-Clean (for low temperature applications)
Flux Classification:	RELO
Flux Activation Temperature:	100°C (212°F)
Color:	Light yellow to orange/brown
Packaging:	Jar 150g
Shelf Life:	Refrigerated >24 months, Unrefrigerated >24 months

Stencil Life

>8 hours @ 20-50% RH 22-28°C (72-82°F)
 >4 hours @ 50-70% RH 22-28°C (72-82°F)

Stencil Cleaning

Automated stencil cleaning systems for both stencil and misprinted boards. Manual cleaning using isopropyl alcohol (IPA).

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Do not freeze. Allow 4 hours for flux to reach an operating temperature of 20-25°C (68-77°F) before use.

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

Conforms to the following Industry Standards:

J-STD-004B, Amendment 1 (Solder Fluxes):	Yes
RoHS 3 Directive (EU) 2015/863:	Yes